Rochester Electronics®

Datasheet

MC10131

Dual Type D Master-Slave Flip-Flop

The MC10131 is a dual master-slave type D flip-flop. Asynchronous Set (S) and Reset (R) override Clock (C_C) and Clock Enable (C_E) inputs. Each flip-flop may be clocked separately by holding the common clock in the low state and using the enable inputs for the clocking function. If the common clock is to be used to clock the flip-flop, the Clock Enable inputs must be in the low state. In this case, the enable inputs perform the function of controlling the common clock.

The output states of the flip-flop change on the positive transition of the clock. A change in the information present at the data (D) input will not affect the output information at any other time due to master slave construction.

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer (OCM).

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FOR REFERENCE ONLY

MC10131

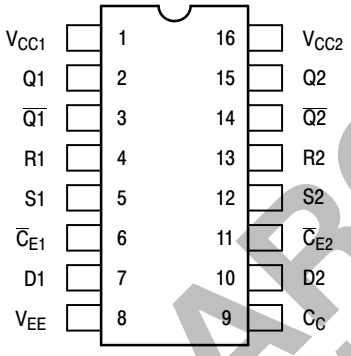
Dual Type D Master-Slave Flip-Flop

The MC10131 is a dual master–slave type D flip–flop. Asynchronous Set (S) and Reset (R) override Clock (C_C) and $\overline{\text{Clock}}$ $\overline{\text{Enable}}$ (C_E) inputs. Each flip–flop may be clocked separately by holding the common clock in the low state and using the enable inputs for the clocking function. If the common clock is to be used to clock the flip–flop, the $\overline{\text{Clock}}$ $\overline{\text{Enable}}$ inputs must be in the low state. In this case, the enable inputs perform the function of controlling the common clock.

The output states of the flip–flop change on the positive transition of the clock. A change in the information present at the data (D) input will not affect the output information at any other time due to master slave construction.

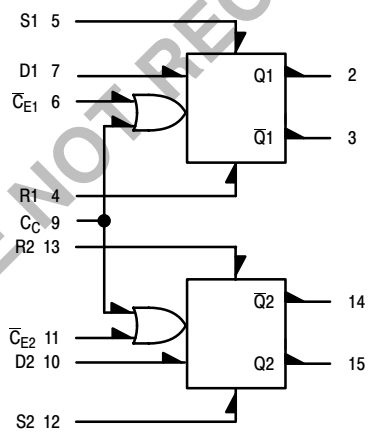
- P_D = 235 mW typ/pkg (No Load)
- F_{Tog} = 160 MHz typ
- t_{pd} = 3.0 ns typ
- t_r, t_f = 2.5 ns typ (20%–80%)

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

LOGIC DIAGRAM

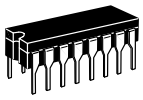


V_{CC1} = PIN 1
V_{CC2} = PIN 16
V_{EE} = PIN 8

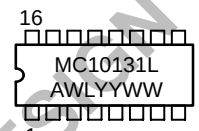
ON Semiconductor

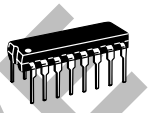
http://onsemi.com

MARKING DIAGRAMS

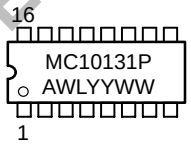


CDIP–16
L SUFFIX
CASE 620

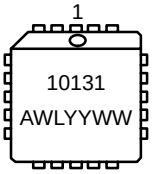




PDIP–16
P SUFFIX
CASE 648



PLCC–20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

CLOCKED TRUTH TABLE

C	D	Q_{n+1}
L	X	Q_n
H	L	L
H	H	H

$C = C_E + C_C$.A clock H is a clock transition from a low to a high state.

R–S TRUTH TABLE

R	S	Q_{n+1}
L	L	Q_n
L	H	H
H	L	L
H	H	N.D.

N.D. = Not Defined

ORDERING INFORMATION

Device	Package	Shipping
MC10131L	CDIP–16	25 Units / Rail
MC10131P	PDIP–16	25 Units / Rail
MC10131FN	PLCC–20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Pin Under Test	Test Limits							Unit
			–30°C		+25°C			+85°C		
			Min	Max	Min	Typ	Max	Min	Max	
Power Supply Drain Current	I_E	8		62		45	56		62	mAdc
Input Current	I_{inH}	4 5 6 7 9		525 525 350 390 425			330 330 220 245 265		330 330 220 245 265	µAdc
	I_{inL}	4, 5* 6, 7, 9*	0.5 0.5		0.5 0.5			0.3 0.3		µAdc
Output Voltage Logic 1	V_{OH}	2 2†	–1.060 –1.060	–0.890 –0.890	–0.960 –0.960		–0.810 –0.810	–0.890 –0.890	–0.700 –0.700	Vdc
Output Voltage Logic 0	V_{OL}	2 3†	–1.890 –1.890	–1.675 –1.675	–1.850 –1.850		–1.650 –1.650	–1.825 –1.825	–1.615 –1.615	Vdc
Threshold Voltage Logic 1	V_{OHA}	2 2†	–1.080 –1.080		–0.980 –0.980			–0.910 –0.910		Vdc
Threshold Voltage Logic 0	V_{OLA}	2 3†		–1.655 –1.655			–1.630 –1.630		–1.595 –1.595	Vdc
Switching Times (50Ω Load) Clock Input										ns
Propagation Delay	t_{9+2-} t_{9+2+} t_{6+2+} t_{6+2-}	2 2 2 2	1.7 1.7 1.7 1.7	4.6 4.6 4.6 4.6	1.8 1.8 1.8 1.8	3.0 3.0 3.0 3.0	4.5 4.5 4.5 4.5	1.8 1.8 1.8 1.8	5.0 5.0 5.0 5.0	
Rise Time (20 to 80%)	t_{2+}	2	1.0	4.6	1.1	2.5	4.5	1.1	4.9	
Fall Time (20 to 80%)	t_{2-}	2	1.0	4.6	1.1	2.5	4.5	1.1	4.9	
Set Input										ns
Propagation Delay	t_{5+2+} t_{12+15+} t_{5+3-} t_{12+14-}	2 15 3 14	1.7 1.7 1.7 1.7	4.4 4.4 4.4 4.4	1.8 1.8 1.8 1.8	2.8 2.8 2.8 2.8	4.3 4.3 4.3 4.3	1.8 1.8 1.8 1.8	4.8 4.8 4.8 4.8	
Reset Input										ns
Propagation Delay	t_{4+2-} t_{13+15-} t_{4+3-} t_{13+14+}	2 15 3 14	1.7 1.7 1.7 1.7	4.4 4.4 4.4 4.4	1.8 1.8 1.8 1.8	2.8 2.8 2.8 2.8	4.3 4.3 4.3 4.3	1.8 1.8 1.8 1.8	4.8 4.8 4.8 4.8	
Setup Time	t_{setup}	7	2.5		2.5			2.5		ns
Hold Time	t_{hold}	7	1.5		1.5			1.5		ns
Toggle Frequency (Max)	f_{tog}	2	125		125	160		125		MHz

* Individually test each input applying V_{IH} or V_{IL} to input under test.

† Output level to be measured after a clock pulse has been applied to the $\overline{C}_E$ Input (Pin 6)

ELECTRICAL CHARACTERISTICS (continued)

			TEST VOLTAGE VALUES (Volts)					
		@ Test Temperature	V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}	
		–30°C	–0.890	–1.890	–1.205	–1.500	–5.2	
		+25°C	–0.810	–1.850	–1.105	–1.475	–5.2	
		+85°C	–0.700	–1.825	–1.035	–1.440	–5.2	
Characteristic	Symbol	Pin Under Test	TEST VOLTAGE APPLIED TO PINS LISTED BELOW					(V_{CC}) Gnd
			V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}	
Power Supply Drain Current	I_E	8					8	1, 16
Input Current	I_{inH}	4 5 6 7 9	4 5 6 7 9				8 8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16
	I_{inL}	4, 5* 6, 7, 9*		* *			8 8	1, 16 1, 16
Output Voltage Logic 1	V_{OH}	2 2†	5 7				8 8	1, 16 1, 16
Output Voltage Logic 0	V_{OL}	2 3†	5 7				8 8	1, 16 1, 16
Threshold Voltage Logic 1	V_{OHA}	2 2†			5 7	 9	8 8	1, 16 1, 16
Threshold Voltage Logic 0	V_{OLA}	2 3†			5 7	 9	8 8	1, 16 1, 16
Switching Times (50Ω Load) Clock Input			**+1.11Vdc**		**Pulse In**	**Pulse Out**	**–3.2 V**	**+2.0 V**
Propagation Delay	t_{9+2-} t_{9+2+} t_{6+2+} t_{6+2-}	2 2 2 2	 7 7 		9 9 6 6	2 2 2 2	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time (20 to 80%)	t_{2+}	2	7		9	2	8	1, 16
Fall Time (20 to 80%)	t_{2-}	2			9	2	8	1, 16
Set Input								
Propagation Delay	t_{5+2+} t_{12+15+} t_{5+3-} t_{12+14-}	2 15 3 14	 6 9		5 12 5 12	2 15 3 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Reset Input								
Propagation Delay	t_{4+2-} t_{13+15-} t_{4+3-} t_{13+14+}	2 15 3 14	 6 9		4 13 4 13	2 15 3 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Setup Time	t_{setup}	7			6, 7	2	8	1, 16
Hold Time	t_{hold}	7			6, 7	2	8	1, 16
Toggle Frequency (Max)	f_{tog}	2			6	2	8	1, 16

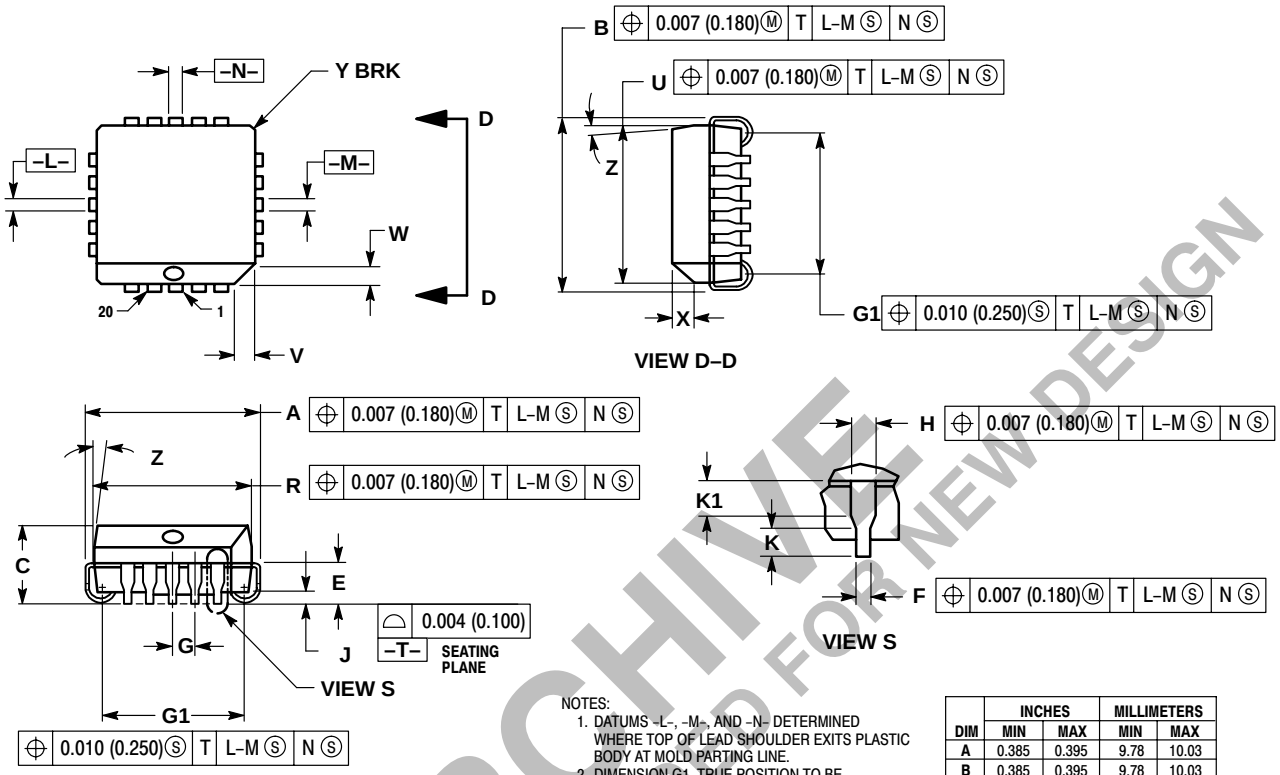
* Individually test each input applying V_{IH} or V_{IL} to input under test.

† Output level to be measured after a clock pulse has been applied to the $\overline{C}_E$ Input (Pin 6)

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC–20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775–02
ISSUE C

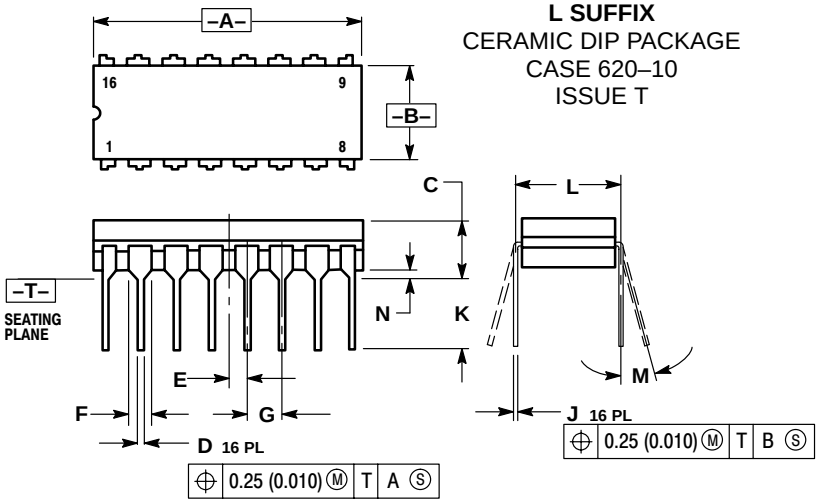


NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

PACKAGE DIMENSIONS

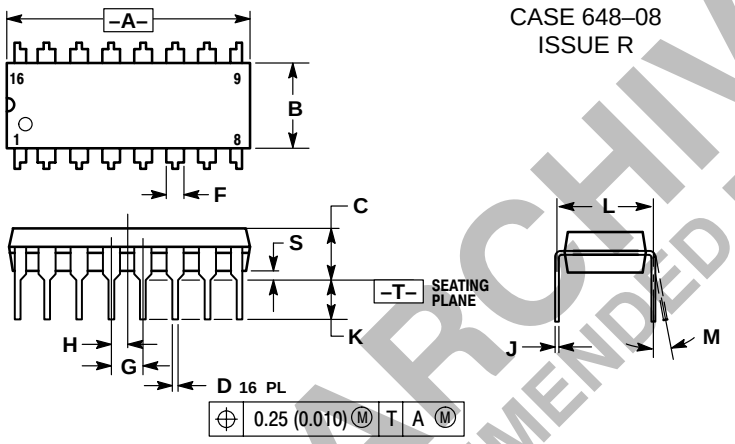
CDIP–16
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

PDIP–16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

Notes

Notes

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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